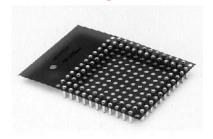
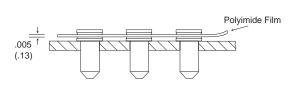
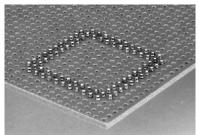
Low Insertion Force Peel-A-Way® PGA Sockets

5 Energy Way, P.O. Box 1019, West Warwick, RI 02893 USA Tel. 800-424-9850/401-823-5200 • Fax 401-823-8723 • Email info@advintcorp.com • Internet http://www.advintcorp.com

Peel-A-Way® Low Insertion Force PGA Sockets







Features:

- Disposable carriers peel away after soldering.
- Peel-A-Way® tabs and full grid wafer supplied on all Peel-A-Way® PGA sockets.
- Maximum air flow under PGA for greater cooling.
- Better flux rinse and cleaning.
- Allows inspection of solder joints on both sides of PCB.
- Lowest profile with use of type -210 terminal.
- Peel-A-Way® disposable socket terminal carrier available in any configuration shown or custom designed to meet your specifications.

Terminals and Contacts:

Terminal: Brass - Copper Alloy (C36000)

ASTM-B-16

Contact: Beryllium Copper (C17200)

ASTM-B-194

Solder Preform:

63% Tin, 37% Lead

Plating:

Terminal: Gold over Nickel or

Tin-Lead over Nickel

Contact: Gold over Nickel or

Tin-Lead over Nickel

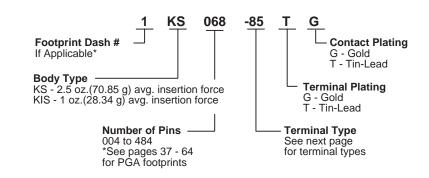
Gold per MIL-G-45204 Tin-Lead per MIL-P-81728 Nickel per QQ-N-290

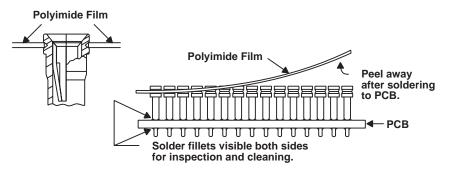
Body Material:

KS/KIS - Polyimide Film

-269°C to 400°C (-452°F to 752°F)

How To Order

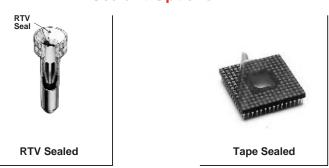




How To Use:

- 1. Place socket in PCB.
- 2. Send PCB and socket through soldering operation.
- 3. Peel away polyimide film carrier.

Sealant Options



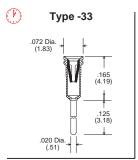
To order: Add RTV to end of part #
Note: RTV not available with HCS or HCIS Insulators

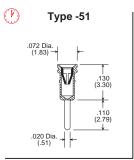
To order: Add 3M to end of part #

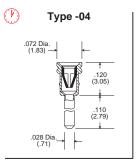
Low Insertion Force Peel-A-Way® PGA Sockets

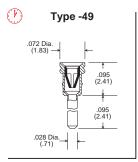
5 Energy Way, P.O. Box 1019, West Warwick, RI 02893 USA Tel. 800-424-9850/401-823-5200 • Fax 401-823-8723 • Email info@advintcorp.com • Internet http://www.advintcorp.com

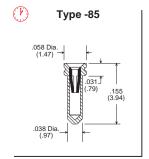
Terminals for Peel-A-Way® Low Insertion Force PGA Sockets Standard Quick Turn Terminals

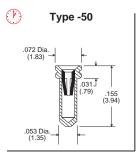
















Quick turn delivery available on standard terminal types.

Additional terminal types available.
See terminal section for detailed terminal information.

Solder Preform PGA Sockets - Intrusive Reflow Application



Polyimide Film Solder Preform PC Board Preform After Solder Flow

Features:

- Combines the labor of socket loading and solder application into one operation.
- Eliminates the use of solder paste and screening operation.
- Eliminates solder bridges and/or solder shorts due to excess solder.
- Insures a reliable solder joint with controlled solder volume.
- Ideal for surface mount and mixed technology applications.
- For custom solder preform terminal applications consult factory.
- See previous page for material specifications and how to order information.

Solder Preform Terminals

